This user's guide provides an overview of the features and options of the BOOSTXL-SHARP128, including power, header pinouts and connections, and communication interfaces.

Figure 1. BOOSTXL-SHARP128 BoosterPack™ Plug-In Module
Contents

1 Board Overview .................................................................................................................................................. 3
  1.1 Introduction .................................................................................................................................................. 3
  1.2 Key Features ................................................................................................................................................ 3
  1.3 What’s Included ........................................................................................................................................ 3
  1.4 First Steps: Example Projects .................................................................................................................. 3
  1.5 Next Steps: Looking Into Provided Code and Examples ........................................................................ 3

2 Hardware ......................................................................................................................................................... 4
  2.1 Block Diagram ........................................................................................................................................... 4
  2.2 BoosterPack Plug-In Module Pinout ......................................................................................................... 4
  2.3 Hardware Features .................................................................................................................................... 5
  2.4 Design Files ................................................................................................................................................ 7
  2.5 Hardware Change Log ............................................................................................................................... 7

3 Software and Additional Resources .............................................................................................................. 7
  3.1 Website for LaunchPad Development Kits ............................................................................................... 7
  3.2 TI Resource Explorer .............................................................................................................................. 7
  3.3 SimpleLink SDKs ....................................................................................................................................... 7
  3.4 MSP430Ware Software ........................................................................................................................... 7
  3.5 Tool Options ............................................................................................................................................... 8
  3.6 Community Resources ............................................................................................................................. 8

4 Schematics ....................................................................................................................................................... 9

List of Figures

1 BOOSTXL-SHARP128 BoosterPack™ Plug-In Module ....................................................................................... 1
2 BOOSTXL-SHARP128 Overview ..................................................................................................................... 4
3 BOOSTXL-SHARP128 Block Diagram ........................................................................................................... 4
4 Connector Pinout for LaunchPad Development Kit and BoosterPack Plug-in Module .................................. 5
5 Schematics ...................................................................................................................................................... 9

List of Tables

1 SD Card Detection Configuration .................................................................................................................. 6
2 LCD Power Configuration ............................................................................................................................ 6
3 Chip Select Pin Configurations .................................................................................................................. 6
4 Hardware Change Log ................................................................................................................................... 7

Trademarks

BoosterPack, LaunchPad, SimpleLink, MSP430Ware, Code Composer Studio, E2E are trademarks of Texas Instruments.
Arm, Keil, RealView are registered trademarks of Arm Limited.
IAR Embedded Workbench is a registered trademark of IAR Systems.
Sharp is a registered trademark of Sharp Microelectronics.
1 Board Overview

1.1 Introduction

The Sharp® 128x128 Memory LCD and microSD Card TI BoosterPack™ Plug-in Module (BOOSTXL-SHARP128) is based on the LS013B7DH03 super-low-power TFT display panel from Sharp Electronics and also features a microSD card expansion slot. Both the LCD and SD card can be controlled using the serial peripheral interface (SPI).

TI MCU LaunchPad™ development kit developers can use this BoosterPack plug-in module to display sensor readings, time, graphics, or other information using the 128-x128-pixel LCD as well as to expand embedded applications with SD card read/write capabilities.

NOTE: The BOOSTXL-SHARP128 supersedes the obsoleted 430BOOST-SHARP96, which used the discontinued Sharp LS013B4DN04 LCD module. The 128x128 LS013B7DH03 and the 96x96 LS013B4DN04 LCD modules are pin-to-pin compatible with reusable firmware and drivers.

1.2 Key Features

- Sharp LS013B7DH03 memory LCD
  - 1.28-inch screen offering 128x128 monochrome pixels
  - Super-low power consumption TFT panel
- microSD card expansion slot (no SD Card included)
- DCDC 3-V to 5-V converter available to also support 5-V Sharp displays

1.3 What's Included

1.3.1 Kit Contents

- 1x BOOSTXL-SHARP128 BoosterPack plug-in module
- 1x quick start guide

1.3.2 Software Examples

- SimpleLink™ SDK
- MSP430Ware™ software

1.4 First Steps: Example Projects

A good method to get familiar with the EVM is by using available example code online. The examples demonstrate the key features of the BoosterPack plug-in module.

3. Choose a LaunchPad development kit that fits your needs - Visit TI's LaunchPad portal
2. Download example code from the SimpleLink SDKs or MSP430Ware - See Section 3
1. Plug the BoosterPack into the LaunchPad
Launch!

1.5 Next Steps: Looking Into Provided Code and Examples

It is now time to start exploring more features of the EVM!

http://www.ti.com/tool/boostxl-sharp128

To get started, you need an integrated development environment (IDE) to explore and start editing the code examples. Refer to Section 3 for more information on IDEs and where to download them.

The available code examples are provided inside the SimpleLink SDKs and MSP430Ware software. All code is licensed under BSD, and TI encourages reuse and modifications to fit specific needs.
2 Hardware

Figure 2 shows an overview of the EVM hardware.

Figure 2. BOOSTXL-SHARP128 Overview

2.1 Block Diagram

Figure 3 shows the block diagram.

Figure 3. BOOSTXL-SHARP128 Block Diagram

2.2 BoosterPack Plug-In Module Pinout

The BOOSTXL-SHARP128 BoosterPack plug-in module adheres to the 40-pin BoosterPack plug-in module pinout standard. This standard aids compatibility between LaunchPad development kits and BoosterPack plug-in modules across the TI ecosystem.

The 40-pin standard is compatible with the 20-pin standard that is used by other LaunchPad development kits and BoosterPack plug-in modules. This allows some subset of functionality of 40-pin BoosterPack plug-in modules to be used with 20-pin LaunchPad development kits.
The BOOSTXL-SHARP128 BoosterPack plug-in module is compatible with all 20-pin and 40-pin LaunchPad development kits that are compliant with the standard. For more information about compatibility between LaunchPad development kits and BoosterPack plug-in modules, visit http://www.ti.com/launchpad.

Figure 4 shows the 40-pin pinout of the BOOSTXL-SHARP128 BoosterPack plug-in module.

NOTE: Some pins are not connected by default, and some functionality can be switched to a different pin on the BoosterPack plug-in module using 0- Ω selection resistors on the bottom of the board.

2.3 Hardware Features

2.3.1 Ultra-Low-Power LCD

The Sharp Microelectronics LS013B7DH03 is a 1.28-inch 128- x 128-pixel monochrome HR-TFT transflective LCD panel. This thin, light, and compact module has 18% reflectivity, 0.2% transmissivity, and super-low-power consumption.

2.3.2 microSD Card Slot

The BOOSTXL-SHARP128 BoosterPack plug-in module features an onboard microSD card slot. This provides another form of data storage for users. The microSD card slot can detect if a card is present by generating an active-low interrupt signal on the SD card detect pin. The SD_DETECT signal can be selected between three different pins of the BoosterPack plug-in module using 0- Ω resistors (see Table 1).
Table 1. SD Card Detection Configuration

<table>
<thead>
<tr>
<th>Selectable Pin Function</th>
<th>Selection Resistor</th>
<th>BoosterPack Plug-in Module Pin</th>
</tr>
</thead>
<tbody>
<tr>
<td>SD_DETECT</td>
<td>R18 (default)</td>
<td>BP Pin 17</td>
</tr>
<tr>
<td></td>
<td>R19</td>
<td>BP Pin 18</td>
</tr>
<tr>
<td></td>
<td>R20</td>
<td>BP Pin 11</td>
</tr>
</tbody>
</table>

2.3.3 Customizable LCD Power

The default setting uses a GPIO pin (BP2) to power the BoosterPack plug-in module at the GPIO voltage of the LaunchPad development kit. This allows removing power from the BoosterPack plug-in module entirely through software on the LaunchPad development kit. It is often beneficial to control the power of the LCD directly, and although the LCD is ultra-low power, completely powering it down can extend battery life.

By modifying the 0-Ω resistors, the setup can be changed to connect to $V_{CC}$ all the time. This frees up one pin on the header of the BoosterPack plug-in module.

Additionally, there is a 3-V to 5-V DC/DC converter on board. In the default configuration this DC/DC converter is completely disconnected. Using 0-Ω resistors or solder bridges the converter can be enabled and the output used to power the display. Resistor R1 or R2 can be populated to supply the input voltage to the DC/DC converter. This can be useful to interface other displays that come with the same connector but require 5 V.

Table 2 lists the possible LCD power sources selectable with 0-Ω resistors on the back of the board.

Table 2. LCD Power Configuration

<table>
<thead>
<tr>
<th>Selectable Pin Function</th>
<th>Selection Resistor</th>
<th>LCD Power Source</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>R7 (default)</td>
<td>GPIO - BP Pin 2</td>
</tr>
<tr>
<td></td>
<td>R1, R6</td>
<td>DC/DC 5V - Onboard (3V3 as DC/DC Vin)</td>
</tr>
<tr>
<td></td>
<td>R2, R6</td>
<td>DC/DC 5V - Onboard (GPIO as DC/DC Vin)</td>
</tr>
<tr>
<td></td>
<td>R5</td>
<td>3V3 - BP Pin 1</td>
</tr>
<tr>
<td></td>
<td>R4</td>
<td>5V - BP Pin 21</td>
</tr>
</tbody>
</table>

2.3.4 Configurable Chip Select Pins

By default, the LCD Chip Select and SDCard Chip Select pins are connected on the J1 BoosterPack header to maintain backwards compatibility with existing software that was developed on the old 430BOOST-SHARP96 and the Card Reader SDCard BoosterPack plug-in module.

However, to provide compatibility with the BoosterPack plug-in module pinout standard, 0-Ω resistors R14 and R16 can be removed, while R15 and R17 can be shorted, to switch the chip select pins from J1 to J2 to conform to the BoosterPack plug-in module standard.

Table 3. Chip Select Pin Configurations

<table>
<thead>
<tr>
<th>Selectable Pin Function</th>
<th>Selection Resistor</th>
<th>BoosterPack Plug-in Module Pin</th>
</tr>
</thead>
<tbody>
<tr>
<td>LCD_SPI_CS</td>
<td>R14 (default)</td>
<td>BP Pin 6</td>
</tr>
<tr>
<td></td>
<td>R15</td>
<td>BP Pin 13</td>
</tr>
<tr>
<td>SD_SPI_CS</td>
<td>R16 (default)</td>
<td>BP Pin 8</td>
</tr>
<tr>
<td></td>
<td>R17</td>
<td>BP Pin 12</td>
</tr>
</tbody>
</table>
2.4 Design Files

2.4.1 Hardware Design Files
Schematics can be found in Section 4. All design files including schematics, layout, bill of materials (BOM), Gerber files, and documentation are available for download in the BOOSTXL-SHARP128 Design Files.

2.5 Hardware Change Log
Table 4 lists the revision history of the BOOSTXL-SHARP128 BoosterPack plug-in module.

Table 4. Hardware Change Log

<table>
<thead>
<tr>
<th>PCB Revision</th>
<th>Date</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>Rev A</td>
<td>August 2018</td>
<td>Production Release</td>
</tr>
</tbody>
</table>

3 Software and Additional Resources

3.1 Website for LaunchPad Development Kits
More information about LaunchPad development kits, supported BoosterPack plug-in modules, and available resources can be found at TI's LaunchPad portal.

3.2 TI Resource Explorer
TI Resource Explorer is a cloud-enabled repository that consolidates everything you need to start your development. Using TI Resource Explorer, you will find code examples, documentation, hardware design files, training, and more. TI Resource Explorer is context-aware, delivering relevant material as you navigate the folder structure to the left.

It is easy to find all of the relevant material associated to your development kit, device, or SDK. Use the search bars above to look for your specific LaunchPad development kit. The content in TI Resource Explorer filters appropriately. The content is in three main sections: Device, Development Tools, and Software.

3.3 SimpleLink SDKs
The SimpleLink SDK is designed for simplified development within one environment using industry standard APIs, TI Drivers, and TI RTOS to provide a robust foundation for application development. Within the SDK, you will find code examples, drivers, middleware, documentation, migration guides, and more.

For more information, visit www.ti.com/simplelinksdk.

3.4 MSP430Ware Software
MSPWare software is a collection of code examples, software libraries, data sheets, and other design resources for all MSP devices delivered in a convenient package – essentially everything developers need to become MSP experts. In addition to providing a complete collection of existing MSP design resources, MSPWare also includes a high-level API called MSP Driver Library. This library makes it easy to program MSP hardware.

For more information, see www.ti.com/tool/mspware.
3.5 Tool Options

The source code installation includes directories containing projects, makefiles, and binaries for the following tool-chains:

- Arm® Keil® RealView® Microcontroller Development System
- IAR Embedded Workbench® for Arm
- TI Code Composer Studio™ IDE for Arm and GCC compilers
- Energia open-source electronics prototyping platform

For detailed information on using the tools, see the documentation included in the tool chain installation or visit the website of the tools supplier.

3.6 Community Resources

3.6.1 TI E2E™ Community

Search the TI E2E community forums at e2e.ti.com. If you cannot find your answer, post your question to the community!

3.6.2 Community at Large

Many online communities focus on the LaunchPad development kit – for example, http://www.43oh.com. You can find additional tools, resources, and support from these communities.
Figure 5. Schematics
STANDARD TERMS FOR EVALUATION MODULES

1. Delivery: TI delivers TI evaluation boards, kits, or modules, including any accompanying demonstration software, components, and/or documentation which may be provided together or separately (collectively, an “EVM” or “EVMs”) to the User (“User”) in accordance with the terms set forth herein. User's acceptance of the EVM is expressly subject to the following terms.

1.1 EVMs are intended solely for product or software developers for use in a research and development setting to facilitate feasibility evaluation, experimentation, or scientific analysis of TI semiconductors products. EVMs have no direct function and are not finished products. EVMs shall not be directly or indirectly assembled as a part or subassembly in any finished product. For clarification, any software or software tools provided with the EVM (“Software”) shall not be subject to the terms and conditions set forth herein but rather shall be subject to the applicable terms that accompany such Software.

1.2 EVMs are not intended for consumer or household use. EVMs may not be sold, sublicensed, leased, rented, loaned, assigned, or otherwise distributed for commercial purposes by Users, in whole or in part, or used in any finished product or production system.

2 Limited Warranty and Related Remedies/Disclaimers:

2.1 These terms do not apply to Software. The warranty, if any, for Software is covered in the applicable Software License Agreement.

2.2 TI warrants that the TI EVM will conform to TI's published specifications for ninety (90) days after the date TI delivers such EVM to User. Notwithstanding the foregoing, TI shall not be liable for a nonconforming EVM if (a) the nonconformity was caused by neglect, misuse or mistreatment by an entity other than TI, including improper installation or testing, or for any EVMs that have been altered or modified in any way by an entity other than TI, (b) the nonconformity resulted from User's design, specifications or instructions for such EVMs or improper system design, or (c) User has not paid on time. Testing and other quality control techniques are used to the extent TI deems necessary. TI does not test all parameters of each EVM. User's claims against TI under this Section 2 are void if User fails to notify TI of any apparent defects in the EVMs within ten (10) business days after delivery, or of any hidden defects with ten (10) business days after the defect has been detected.

2.3 TI's sole liability shall be at its option to repair or replace EVMs that fail to conform to the warranty set forth above, or credit User's account for such EVM. TI's liability under this warranty shall be limited to EVMs that are returned during the warranty period to the address designated by TI and that are determined by TI not to conform to such warranty. If TI elects to repair or replace such EVM, TI shall have a reasonable time to repair such EVM or provide replacements. Repaired EVMs shall be warranted for the remainder of the original warranty period. Replaced EVMs shall be warranted for a new full ninety (90) day warranty period.

3 Regulatory Notices:

3.1 United States

3.1.1 Notice applicable to EVMs not FCC-Approved:

FCC NOTICE: This kit is designed to allow product developers to evaluate electronic components, circuitry, or software associated with the kit to determine whether to incorporate such items in a finished product and software developers to write software applications for use with the end product. This kit is not a finished product and when assembled may not be resold or otherwise marketed unless all required FCC equipment authorizations are first obtained. Operation is subject to the condition that this product not cause harmful interference to licensed radio stations and that this product accept harmful interference. Unless the assembled kit is designed to operate under part 15, part 18 or part 95 of this chapter, the operator of the kit must operate under the authority of an FCC license holder or must secure an experimental authorization under part 5 of this chapter.

3.1.2 For EVMs annotated as FCC – FEDERAL COMMUNICATIONS COMMISSION Part 15 Compliant:

CAUTION

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation. Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

FCC Interference Statement for Class A EVM devices

NOTE: This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.
FCC Interference Statement for Class B EVM devices

NOTE: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

3.2 Canada

3.2.1 For EVMs issued with an Industry Canada Certificate of Conformance to RSS-210 or RSS-247

Concerning EVMs Including Radio Transmitters:

This device complies with Industry Canada license-exempt RSSs. Operation is subject to the following two conditions:

(1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Concernant les EVMs avec appareils radio:

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L’exploitation est autorisée aux deux conditions suivantes: (1) l’appareil ne doit pas produire de brouillage, et (2) l’utilisateur de l’appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d’en compromettre le fonctionnement.

Concerning EVMs Including Detachable Antennas:

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication. This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Concernant les EVMs avec antennes détachables

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante. Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.

3.3 Japan

3.3.1 Notice for EVMs delivered in Japan: Please see http://www.tij.co.jp/lnds/lt_ja/general/eStore/notice_01.page 日本国内に輸入される評価用キット、ボードについては、次のところをご覧ください。
http://www.tij.co.jp/lnds/lt_ja/general/eStore/notice_01.page

3.3.2 Notice for Users of EVMs Considered “Radio Frequency Products” in Japan: EVMs entering Japan may not be certified by TI as conforming to Technical Regulations of Radio Law of Japan.

If User uses EVMs in Japan, not certified to Technical Regulations of Radio Law of Japan, User is required to follow the instructions set forth by Radio Law of Japan, which includes, but is not limited to, the instructions below with respect to EVMs (which for the avoidance of doubt are stated strictly for convenience and should be verified by User):

1. Use EVMs in a shielded room or any other test facility as defined in the notification #173 issued by Ministry of Internal Affairs and Communications on March 28, 2006, based on Sub-section 1.1 of Article 6 of the Ministry’s Rule for Enforcement of Radio Law of Japan.

2. Use EVMs only after User obtains the license of Test Radio Station as provided in Radio Law of Japan with respect to EVMs, or

3. Use of EVMs only after User obtains the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to EVMs. Also, do not transfer EVMs, unless User gives the same notice above to the transferee. Please note that if User does not follow the instructions above, User will be subject to penalties of Radio Law of Japan.
【無線電波を送信する製品の開発キットをお使いになる際の注意事項】開発キットの中には技術基準適合証明を受けていないものがあります。 技術適合証明を受けていないものをご使用に際しては、電波法遵守のため、以下のいずれかの措置を取っていただく必要がありますのでご注意ください。

1. 電波法施行規則第6条第1項第1号に基づく平成18年3月28日総務省告示第173号で定められた電波暗室等の試験設備でご使用いただく。
2. 実験局の免許を取得後ご利用いただく。
3. 技術基準適合証明を取得後ご利用いただく。

なお、本製品は、上記の「ご使用にあたっての注意」を譲渡先、移転先に通知しない限り、譲渡、移転できないものとします。

日本テキサス・インスツルメンツ株式会社
東京都新宿区西新宿6丁目24番1号
西新宿三井ビル

3.3.3 Notice for EVMs for Power Line Communication: Please see http://www.tij.co.jp/ltsd/ti_ja/general/eStore/notice_02.page
電力線搬送波通信についての開発キットをお使いになる際の注意事項については、次のところをご覧ください。http://www.tij.co.jp/ltsd/ti_ja/general/eStore/notice_02.page

4. EVM Use Restrictions and Warnings:

4.1 EVMS ARE NOT FOR USE IN FUNCTIONAL SAFETY AND/OR SAFETY CRITICAL EVALUATIONS, INCLUDING BUT NOT LIMITED TO EVALUATIONS OF LIFE SUPPORT APPLICATIONS.

4.2 User must read and apply the user guide and other available documentation provided by TI regarding the EVM prior to handling or using the EVM, including without limitation any warning or restriction notices. The notices contain important safety information related to, for example, temperatures and voltages.

4.3 Safety-Related Warnings and Restrictions:

4.3.1 User shall operate the EVM within TI’s recommended specifications and environmental considerations stated in the user guide, other available documentation provided by TI, and any other applicable requirements and employ reasonable and customary safeguards. Exceeding the specified performance ratings and specifications (including but not limited to input and output voltage, current, power, and environmental ranges) for the EVM may cause personal injury or death, or property damage. If there are questions concerning performance ratings and specifications, User should contact a TI field representative prior to connecting interface electronics including input power and intended loads. Any loads applied outside of the specified output range may also result in unintended and/or inaccurate operation and/or possible permanent damage to the EVM and/or interface electronics. Please consult the EVM user guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative.

4.3.2 EVMs are intended solely for use by technically qualified, professional electronics experts who are familiar with the dangers and application risks associated with handling electrical mechanical components, systems, and subsystems. User assumes all responsibility and liability for proper and safe handling and use of the EVM by User or its employees, affiliates, contractors or designees. User assumes all responsibility and liability to ensure that any interfaces (electronic and/or mechanical) between the EVM and any human body are designed with suitable isolation and means to safely limit accessible leakage currents to minimize the risk of electrical shock hazard. User assumes all responsibility and liability for any improper or unsafe handling or use of the EVM by User or its employees, affiliates, contractors or designees.

4.4 User assumes all responsibility and liability to determine whether the EVM is subject to any applicable international, federal, state, or local laws and regulations related to User’s handling and use of the EVM and, if applicable, User assumes all responsibility and liability for compliance in all respects with such laws and regulations. User assumes all responsibility and liability for proper disposal and recycling of the EVM consistent with all applicable international, federal, state, and local requirements.

5. Accuracy of Information: To the extent TI provides information on the availability and function of EVMs, TI attempts to be as accurate as possible. However, TI does not warrant the accuracy of EVM descriptions, EVM availability or other information on its websites as accurate, complete, reliable, current, or error-free.
6. **Disclaimers:**

6.1 EXCEPT AS SET FORTH ABOVE, EVMS AND ANY MATERIALS PROVIDED WITH THE EVM (INCLUDING, BUT NOT LIMITED TO, REFERENCE DESIGNS AND THE DESIGN OF THE EVM ITSELF) ARE PROVIDED "AS IS" AND "WITH ALL FAULTS." TI DISCLAIMS ALL OTHER WARRANTIES, EXPRESS OR IMPLIED, REGARDING SUCH ITEMS, INCLUDING BUT NOT LIMITED TO ANY EPIDEMIC FAILURE WARRANTY OR IMPLIED WARRANTIES OF MERCHANTABILITY OR FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF ANY THIRD PARTY PATENTS, COPYRIGHTS, TRADESECRETS OR OTHER INTELLECTUAL PROPERTY RIGHTS.

6.2 EXCEPT FOR THE LIMITED RIGHT TO USE THE EVM SET FORTH HEREIN, NOTHING IN THESE TERMS SHALL BE CONSTRUED AS GRANTING OR CONFERRING ANY RIGHTS BY LICENSE, PATENT, OR ANY OTHER INDUSTRIAL OR INTELLECTUAL PROPERTY RIGHT OF TI, ITS SUPPLIERS/LICENSORS OR ANY OTHER THIRD PARTY, TO USE THE EVM IN ANY FINISHED END-USER OR READY-TO-USE FINAL PRODUCT, OR FOR ANY INVENTION, DISCOVERY OR IMPROVEMENT, REGARDLESS OF WHEN MADE, CONCEIVED OR ACQUIRED.

7. **USER'S INDEMNITY OBLIGATIONS AND REPRESENTATIONS.** USER WILL DEFEND, INDEMNIFY AND HOLD TI, ITS LICENSORS AND THEIR REPRESENTATIVES HARMLESS FROM AND AGAINST ANY AND ALL CLAIMS, DAMAGES, LOSSES, EXPENSES, COSTS AND LIABILITIES (COLLECTIVELY, "CLAIMS") ARISING OUT OF OR IN CONNECTION WITH ANY HANDLING OR USE OF THE EVM THAT IS NOT IN ACCORDANCE WITH THESE TERMS. THIS OBLIGATION SHALL APPLY WHETHER CLAIMS ARISE UNDER STATUTE, REGULATION, OR THE LAW OF TORT, CONTRACT OR ANY OTHER LEGAL THEORY, AND EVEN IF THE EVM FAILS TO PERFORM AS DESCRIBED OR EXPECTED.

8. **Limitations on Damages and Liability:**

8.1 **General Limitations.** IN NO EVENT SHALL TI BE LIABLE FOR ANY SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL, OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF THESE TERMS OR THE USE OF THE EVMS, REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES. EXCLUDED DAMAGES INCLUDE, BUT ARE NOT LIMITED TO, COST OF REMOVAL OR REINSTALLATION, ANCILLARY COSTS TO THE PROCUREMENT OF SUBSTITUTE GOODS OR SERVICES, RETESTING, OUTSIDE COMPUTER TIME, LABOR COSTS, LOSS OF GOODWILL, LOSS OF PROFITS, LOSS OF SAVINGS, LOSS OF USE, LOSS OF DATA, OR BUSINESS INTERRUPTION. NO CLAIM, SUIT OR ACTION SHALL BE BROUGHT AGAINST TI MORE THAN TWELVE (12) MONTHS AFTER THE EVENT THAT GAVE RISE TO THE CAUSE OF ACTION HAS OCCURRED.

8.2 **Specific Limitations.** IN NO EVENT SHALL TI'S AGGREGATE LIABILITY FROM ANY USE OF AN EVM PROVIDED HEREUNDER, INCLUDING FROM ANY WARRANTY, INDEMNITY OR OTHER OBLIGATION ARISING OUT OF OR IN CONNECTION WITH THESE TERMS, EXCEED THE TOTAL AMOUNT PAID TO TI BY USER FOR THE PARTICULAR EVM(S) AT ISSUE DURING THE PRIOR TWELVE (12) MONTHS WITH RESPECT TO WHICH LOSSES OR DAMAGES ARE CLAIMED. THE EXISTENCE OF MORE THAN ONE CLAIM SHALL NOT ENLARGE OR EXTEND THIS LIMIT.

9. **Return Policy.** Except as otherwise provided, TI does not offer any refunds, returns, or exchanges. Furthermore, no return of EVM(s) will be accepted if the package has been opened and no return of the EVM(s) will be accepted if they are damaged or otherwise not in a resalable condition. If User feels it has been incorrectly charged for the EVM(s) it ordered or that delivery violates the applicable order, User should contact TI. All refunds will be made in full within thirty (30) working days from the return of the components(s), excluding any postage or packaging costs.

10. **Governing Law:** These terms and conditions shall be governed by and interpreted in accordance with the laws of the State of Texas, without reference to conflict-of-laws principles. User agrees that non-exclusive jurisdiction for any dispute arising out of or relating to these terms and conditions lies within courts located in the State of Texas and consents to venue in Dallas County, Texas. Notwithstanding the foregoing, any judgment may be enforced in any United States or foreign court, and TI may seek injunctive relief in any United States or foreign court.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2018, Texas Instruments Incorporated
IMPORTANT NOTICE FOR TI DESIGN INFORMATION AND RESOURCES

Texas Instruments Incorporated ('TI') technical, application or other design advice, services or information, including, but not limited to, reference designs and materials relating to evaluation modules, (collectively, “TI Resources”) are intended to assist designers who are developing applications that incorporate TI products; by downloading, accessing or using any particular TI Resource in any way, you (individually or, if you are acting on behalf of a company, your company) agree to use it solely for this purpose and subject to the terms of this Notice.

TI's provision of TI Resources does not expand or otherwise alter TI's applicable published warranties or warranty disclaimers for TI products, and no additional obligations or liabilities arise from TI providing such TI Resources. TI reserves the right to make corrections, enhancements, improvements and other changes to its TI Resources.

You understand and agree that you remain responsible for using your independent analysis, evaluation and judgment in designing your applications and that you have full and exclusive responsibility to assure the safety of your applications and compliance of your applications (and of all TI products used in or for your applications) with all applicable regulations, laws and other applicable requirements. You represent that, with respect to your applications, you have all the necessary expertise to create and implement safeguards that (1) anticipate dangerous consequences of failures, (2) monitor failures and their consequences, and (3) lessen the likelihood of failures that might cause harm and take appropriate actions. You agree that prior to using or distributing any applications that include TI products, you will thoroughly test such applications and the functionality of such TI products as used in such applications. TI has not conducted any testing other than that specifically described in the published documentation for a particular TI Resource.

You are authorized to use, copy and modify any individual TI Resource only in connection with the development of applications that include the TI product(s) identified in such TI Resource. NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT OF TI OR ANY THIRD PARTY IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information regarding or referencing third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of TI Resources may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI RESOURCES ARE PROVIDED "AS IS" AND WITH ALL FAULTS. TI DISCLAIMS ALL OTHER WARRANTIES OR REPRESENTATIONS, EXPRESS OR IMPLIED, REGARDING TI RESOURCES OR USE THEREOF, INCLUDING BUT NOT LIMITED TO ACCURACY OR COMPLETENESS, TITLE, ANY EPIDEMIC FAILURE WARRANTY AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY YOU AGAINST ANY CLAIM, INCLUDING BUT NOT LIMITED TO ANY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON ANY COMBINATION OF PRODUCTS EVEN IF DESCRIBED IN TI RESOURCES OR OTHERWISE. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, DIRECT, SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF TI RESOURCES OR USE THEREOF, AND REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.

You agree to fully indemnify TI and its representatives against any damages, costs, losses, and/or liabilities arising out of your non-compliance with the terms and provisions of this Notice.

This Notice applies to TI Resources. Additional terms apply to the use and purchase of certain types of materials, TI products and services. These include, without limitation, TI's standard terms for semiconductor products http://www.ti.com/sc/docs/stdterms.htm), evaluation modules, and samples (http://www.ti.com/sc/docs/sampterms.htm).

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2018, Texas Instruments Incorporated